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Robert J. Jacobson

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Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A sealing material for a semiconductor device, which is a sealing material comprising a fluororubber as a rubber component, wherein: the fluororubber inevitably comprises a cured product of a vinylidene fluoride/ hexafluoropropylene/ tetrafluoroethylene elastic copolymer; and copolymerization ratios of respective monomers in the vinylidene fluoride/ hexafluoropropylene/ tetrafluoroethylene elastic copolymer are such that: a content of vinylidene fluoride is in the range of from 25 to 70 mol %; a content of hexafluoropropylene is in the range of from 15 to 60 mol %; a content of tetrafluoroethylene is in the range of from 15 to 60 mol %; and a fluorine content in the vinylidene fluoride/ hexafluoropropylene/ tetrafluoroethylene elastic copolymer is in the range of from 71.5 to 75 mass %, wherein curing of the vinylidene fluoride/ hexafluoropropylene/ tetrafluoroethylene elastic copolymer is performed by irradiation with ionizing radiation, and wherein the sealing material does not include an unsaturated polyfunctional compound.

2. (canceled).

3. (currently amended) The sealing material for a semiconductor device according to claim 1 or 2, wherein a fluorine content of the vinylidene fluoride/ hexafluoropropylene/ tetrafluoroethylene elastic copolymer is in the range of from 72 to 74.5 mass %.

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4. (currently amended) The sealing material for a semiconductor device according to claim [[2]] 1, wherein an irradiation dose of the ionizing radiation is in the range of from 10 to 500 kGy.

5. (withdrawn) A sealing material for a semiconductor device, which is obtained by crosslinking, with ionizing radiation, a fluororubber preform comprising:

i) a fluororubber component (a) comprising a vinylidene fluoride/ hexafluoropropylene elastic copolymer and/or a vinylidene fluoride/ hexafluoropropylene/ tetrafluoroethylene elastic copolymer; and

ii) a non-elastic fluororesin component (b) comprising a vinylidene fluoride (co)polymer in composition of the fluororesin component (b) of 1 to 50 parts by mass relative to 100 parts by mass of the fluororubber component (a).

6. (withdrawn) The sealing material for a semiconductor device according to claim 5, wherein a copolymerization ratio of respective monomers in the vinylidene fluoride/ hexafluoropropylene elastic copolymer is vinylidene fluoride/ hexafluoropropylene = (50 to 95)/(5 to 50) (in mol %).

7. (withdrawn) The sealing material for a semiconductor device according to claim 5 or 6, wherein a copolymerization ratio of respective monomers in the vinylidene fluoride/ hexafluoropropylene/ tetrafluoroethylene elastic copolymer is vinylidene fluoride/ hexafluoropropylene/ tetrafluoroethylene = (20 to 80)/(10 to 70)/(10 to 70) (in mol %).

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8. (withdrawn) The sealing material for a semiconductor device according to claim 5 or 6, wherein a fluorine content of the fluororubber component (a) is in the range of from 65 to 75 mass %.

9. (withdrawn) The sealing material for a semiconductor device according to claim 5 or 6, wherein a ratio of the fluororubber component (a) and the fluororesin component (b) is 5 to 20 parts by mass of the fluororesin component (b) relative to 100 parts by mass of the fluororubber component (a).

10. (withdrawn) The sealing material for a semiconductor device according to claim 5 or 6, wherein an irradiation dose of the ionizing radiation is in the range of from 10 to 500 kGy.

11. (withdrawn) A manufacturing method for a sealing material for a semiconductor device, comprising the steps of:

i) mixing a fluororubber component (a) with a non-elastic fluororesin component (b) to obtain a mixture, wherein the fluororubber component (a) comprises a vinylidene fluoride/ hexafluoropropylene elastic copolymer and/or a vinylidene fluoride/ hexafluoropropylene/ tetrafluoroethylene elastic copolymer, wherein the non-elastic fluororesin component (b) comprises a vinylidene fluoride (co)polymer, wherein 100 parts by mass of the fluororubber component (a) is mixed with 1 to 50 parts by mass of the non-elastic fluororesin component (b) at a temperature of a melting point of the fluororesin component (b) or higher;

ii) preforming the mixture to obtain a preform; and

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iii) irradiating the preform with ionizing radiation.

12. (new) The sealing material for a semiconductor device according to claim 4, wherein the content of vinylidene fluoride is in a range of 29 to 36 mol %; the content of hexafluoropropylene is in a range of 26 to 28 mol %; the content of tetrafluoroethylene is in a range of 38 to 43 mol %; and the fluorine content in the vinylidene fluoride/ hexafluoropropylene/ tetrafluoroethylene elastic copolymer is in a range of 72.2 to 75 mass %.

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